

Title (en)  
CURABLE EPOXY RESIN COMPOSITION

Title (de)  
HÄRTBARE EPOXIDHARZZUSAMMENSETZUNG

Title (fr)  
COMPOSITION DE RÉSINE ÉPOXYDE DURCISSABLE

Publication  
**EP 2736941 A1 20140604 (EN)**

Application  
**EP 11738229 A 20110729**

Priority  
EP 2011063148 W 20110729

Abstract (en)  
[origin: WO2013017149A1] Curable epoxy resin composition comprising a defined aromatic epoxy resin component and a defined latent catalyst system, and optionally further additives, said curable composition being a single epoxy resin composition having a prolonged pot life at a processing temperature within the range of 40 °C to 70 °C, wherein: (a) the epoxy resin component is a compound of formula (I) in monomeric form or in a low polymeric form thereof, or is a mixture of such compounds: formula (I); D = -CH<sub>2</sub>-, -C(CH<sub>3</sub>)<sub>2</sub>-, -S-, -O-, -SO<sub>2</sub>-, -CO-; n = zero or one; said epoxy resin component having an inherent viscosity within the range of 80 mPas to 300 mPas, measured at a temperature of 50 °C; (b) the latent catalyst system comprises at least one metal acetylacetonate and at least one phenolic compound.

IPC 8 full level  
**C08G 59/18** (2006.01); **C08G 59/24** (2006.01); **C08G 59/68** (2006.01); **C08L 63/00** (2006.01); **H01B 3/40** (2006.01)

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**C08G 59/18** (2013.01 - EP KR US); **C08G 59/245** (2013.01 - EP KR US); **C08G 59/68** (2013.01 - EP KR US); **C08L 63/00** (2013.01 - EP KR US); **H01B 3/40** (2013.01 - EP KR US)

Citation (search report)  
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